Authorized Representative* Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information Terminal Plating / Grid Array Material Title - Representative Product Enviro Compliance NA Product-Env-Stewards@onse Version Manufacturing Site Weight* UOM 2024-05-18 TSCBE 339.995 mg	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.					
Company name* Company unique ID Unique ID Authority Response Date* 2024-05-18 Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-Stewa						
Title - Contact Name Product-Env-Stewards Unthorized Representative* Product-Env-Stewards P						
Title - Contact* Product-Env-Stewards Product-Env-S	Response Date*					
Product-Env-Stewards uthorized Representative* Title - Representative Product-Env-Stewards Pr	2024-05-18					
Title - Representative Phone - Representative Phone - Representative Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Onse Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM EGP20A HER DO15 GPPN 2A 50V 2024-05-18 TSCBE 339.995 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow	Email - Contact*					
Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM LEGP20A HER DO15 GPPN 2A 50V Description Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow	Product-Env-Stewards@onsemi.com					
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EGP20A HER DO15 GPPN 2A 50V 2024-05-18 TSCBE 339.995 mg Ianufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflox	Product-Env-Stewards@onsemi.com					
Instruction Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow	Unit Type					
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow	Each					
Matte Tin (Sn) - annealed CTI Alloy NA 0 C 30 seconds 3	Cycles					
Figure 1 m (bh) aimeaca Co 1 moj 1 m C D Seconds C						
omments						
or more information regarding material composition please refer to page 3						

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provid										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.095		Supplier	Silicon (Si)	7440-21-3		0.9855	mg
			В	Nickel (Ni)	7440-02-0		0.0071	mg
			Supplier	Gold (Au)	7440-57-5		0.0016	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.1007	mg
Die Attach Solder	3.5	mg	Supplier	Silver (Ag)	7440-22-4		0.0875	mg
			A	Lead (Pb)	7439-92-1	7a	3.2375	mg
			Supplier	Tin (Sn)	7440-31-5		0.175	mg
Lead Wire	294.8		Supplier	Iron (Fe)	7439-89-6		0.2358	mg
			Supplier	Copper (Cu)	7440-50-8		294.5052	mg
			Supplier	Phosphorus (P)	7723-14-0		0.059	mg
Marking Ink	0.2	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.01	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.01	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.02	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.13	mg
			Supplier	Aluminum (Al)	7429-90-5		0.03	mg
Mold Compound-Black	38.0			Metal Hydroxide	proprietary data		1.786	mg
			Supplier	Carbon Black (C)	1333-86-4		0.114	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		30.4	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		3.8	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.9	mg
Plating	2.4	mg	Supplier	Tin (Sn)	7440-31-5		2.4	mg